

Please delete and replace the paragraph at page 4, lines 20 to 25, to read as follows:

Furthermore, while the nickel-tungsten alloy plating as it is has a hardness of approximately Hv. 600, this plating after being heated and thus cured can be as hard as Hv. 1350. In contrast, if a nickel-tungsten alloy plating with a tungsten content of approximately 10% by weight is heated and thus cured, it does not cure in separation and can only have a hardness of approximately Hv. 600, i.e. the same hardness of such a plating which has not been further processed.

Please delete and replace the paragraph at page 6, lines 3 to 5, to read as follows:

Fig. 1 is a schematic, partial vertical cross section of a die used for sealing an electronic component with resin to mold the electronic component in one embodiment of the present invention; and

Please delete and replace the paragraph at page 6, lines 6 and 7, to read as follows:

Fig. 2 is an enlarged, schematic, partial vertical cross section of a main portion of the Fig. 1 die.

Please delete and replace the paragraph at page 7, lines 18 to 21, to read as follows:

After the passage of a period of time required for curing the melted resin material, dies 1 and 2 are opened

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